

## FJ4B01120L1

## Single P-channel MOS FET

### ■ Features

- Drain-source On-state Resistance :  $R_{DS(on)}$  typ. = 40 m $\Omega$  (  $V_{GS} = -2.5$  V )
- CSP( Chip Size Package )
- Halogen-free / RoHS compliant ( EU RoHS / UL-94 V-0 / MSL : Level 1 )

### ■ Marking Symbol : 1F

### ■ Packaging

Embossed type ( Thermo-compression sealing ) : 1 000 pcs / reel ( standard )

### ■ Absolute Maximum Ratings $T_a = 25$ °C

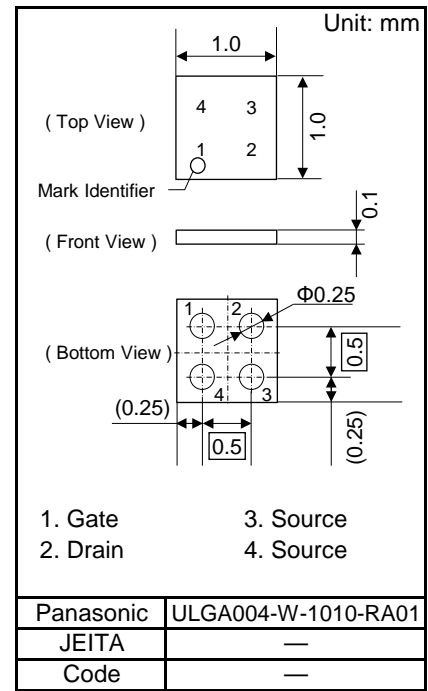
Parameter	Symbol	Rating	Unit	
Drain-source Voltage	$V_{DS}$	-12	V	
Gate-source Voltage	$V_{GS}$	$\pm 8$	V	
Drain Current	DC	$ID1$ <sup>*1</sup>	-2.6	A
		$ID2$ <sup>*2</sup>	-4.2	A
		$ID3$ <sup>*3</sup>	-5.4	A
	Pulsed <sup>*4</sup>	$IDp1$	-20	A
		$IDp2$	-33	A
		$IDp3$	-43	A
Total Power Dissipation	$PD1$ <sup>*1</sup>	0.37	W	
	$PD2$ <sup>*2</sup>	0.94	W	
	$PD3$ <sup>*3</sup>	1.5	W	
Channel Temperature	$T_{ch}$	150	°C	
Operating Ambient Temperature	$T_{opr}$	-40 to +85	°C	
Storage Temperature Range	$T_{stg}$	-55 to +150	°C	

Note \*1 FR4 board (25.4mm×25.4mm×1.0mm), Min Cu 36mm<sup>2</sup> Copper.

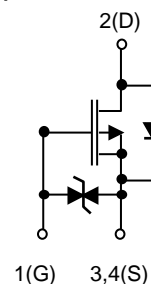
\*2 FR4 board (25.4mm×25.4mm×1.0mm), Full Cu.

\*3 Ceramic substrate (70mm×70mm×1.0mm).

\*4  $t = 10$   $\mu$ s, Duty Cycle  $\leq 1$  %



### Equivalent circuit



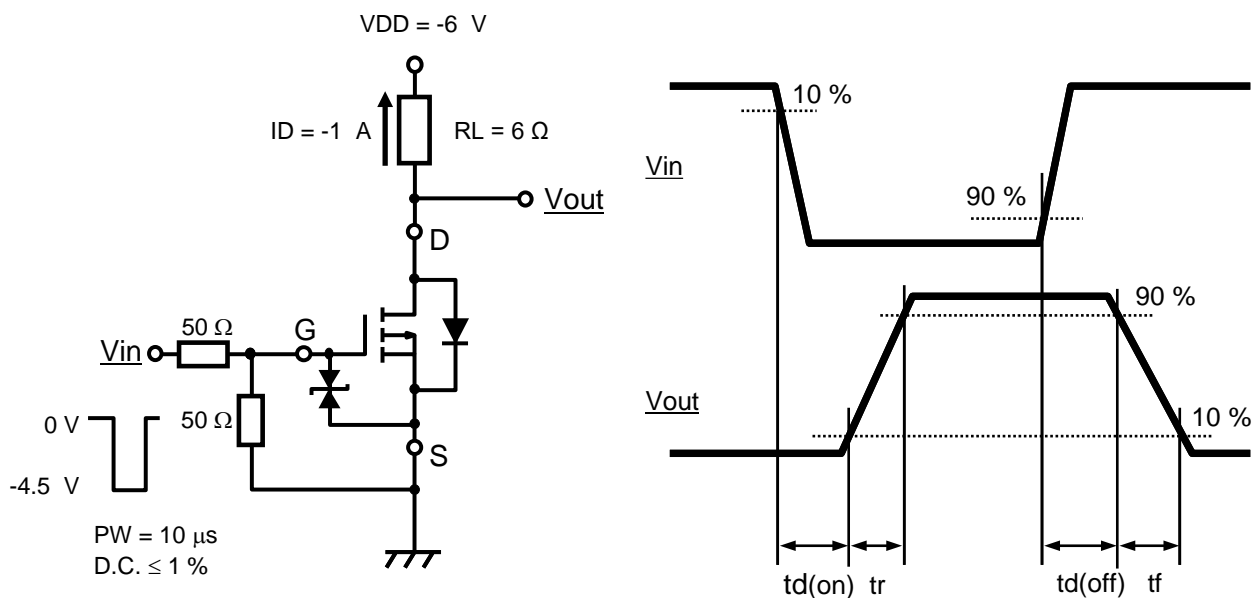
### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source Breakdown Voltage	VDSS	ID = -1 mA, VGS = 0	-12			V
Zero Gate Voltage Drain Current	IDSS	VDS = -12 V, VGS = 0			-1	μA
Gate-source Leakage Current	IGSS	VGS = ±8 V, VDS = 0 V			±10	μA
Gate-source Threshold Voltage	Vth	ID = -2 mA, VDS = -10 V	-0.3		-1.0	V
Drain-source On-state Resistance	RDS(on)1	ID = -2 A, VGS = -4.5 V		34	51	mΩ
	RDS(on)2	ID = -2 A, VGS = -2.5 V		40	61	
	RDS(on)3	ID = -0.2 A, VGS = -1.8 V		48	85	
	RDS(on)4	ID = -0.1 A, VGS = -1.5 V		57	170	
Body Diode Forward Voltage	VF(s-d)	IF = -0.2 A, VGS = 0 V		-0.7	-1.2	V
Input Capacitance <sup>*1</sup>	Ciss	VDS = -10 V, VGS = 0 V f = 1 MHz		814		pF
Output Capacitance <sup>*1</sup>	Coss			201		
Reverse Transfer Capacitance <sup>*1</sup>	Crss			187		
Turn-on Delay Time <sup>*1,*2</sup>	td(on)	VDD = -6 V, VGS = 0 to -4.5 V		6		ns
Rise Time <sup>*1,*2</sup>	tr	ID = -1 A		4		
Turn-off Delay Time <sup>*1,*2</sup>	td(off)	VDD = -6 V, VGS = -4.5 to 0 V		63		
Fall Time <sup>*1,*2</sup>	tf	ID = -1 A		46		
Total Gate Charge <sup>*1</sup>	Qg	VDD = -6 V, VGS = -4.5 V ID = -1 A		10.7		nC
Gate-source Charge <sup>*1</sup>	Qgs			1.4		
Gate-drain Charge <sup>*1</sup>	Qgd			2.1		

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

\*1 Guaranteed by design, not subject to production testing.

\*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time.



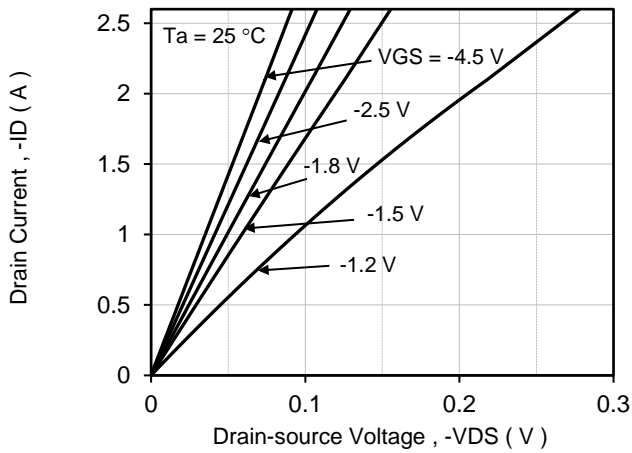
### ■ Electrical State Discharge Characteristics

Standard	Test Type	Symbol	Conditions	Class	Value	Unit
AEC-Q101	Human Body Model	HBM	C = 100 pF, R = 1.5 kΩ	H1C	> 1k to ≤ 2k	V
	Machine Model	MM	C = 200 pF, R = 0 Ω	M2	> 100 to ≤ 200	V

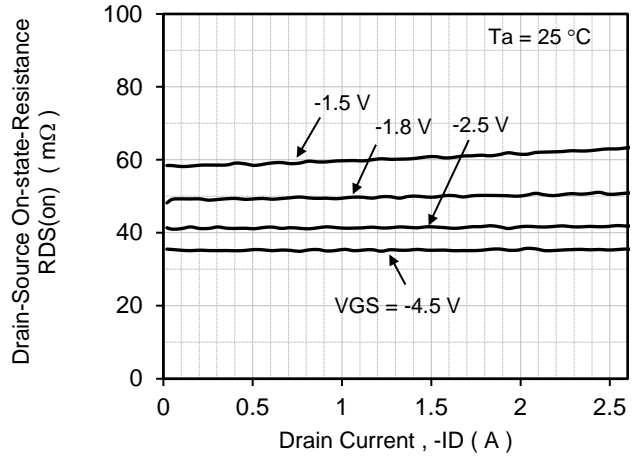


Technical Data ( reference )

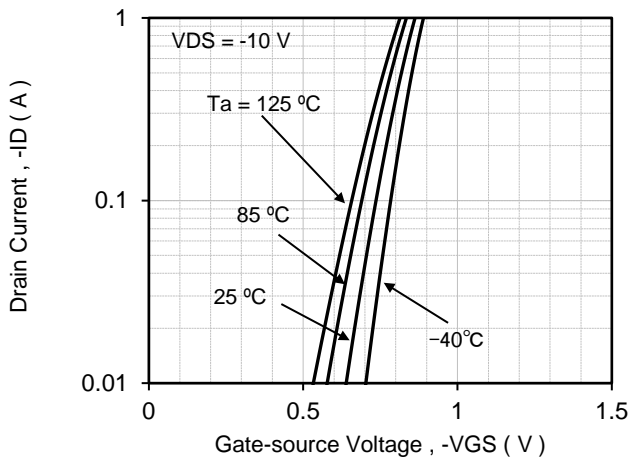
ID - VDS<sup>\*1</sup>



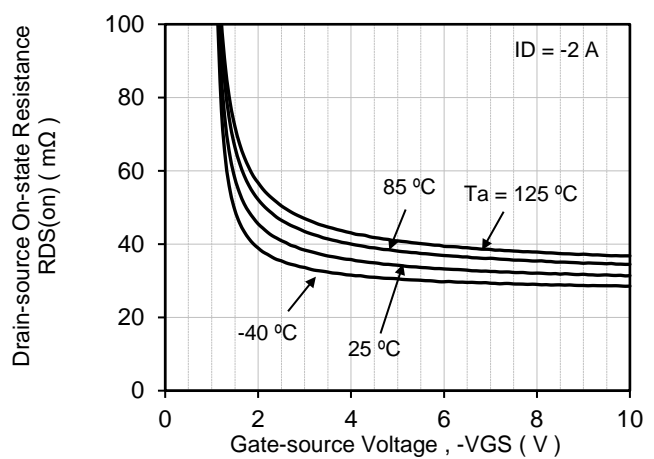
RDS(on) - ID<sup>\*1</sup>



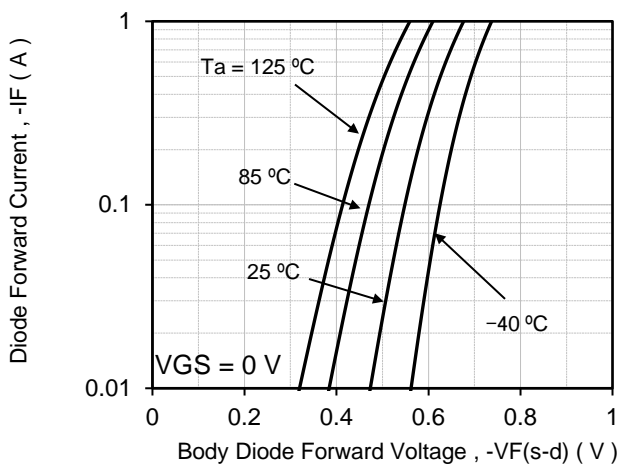
ID - VGS<sup>\*1</sup>



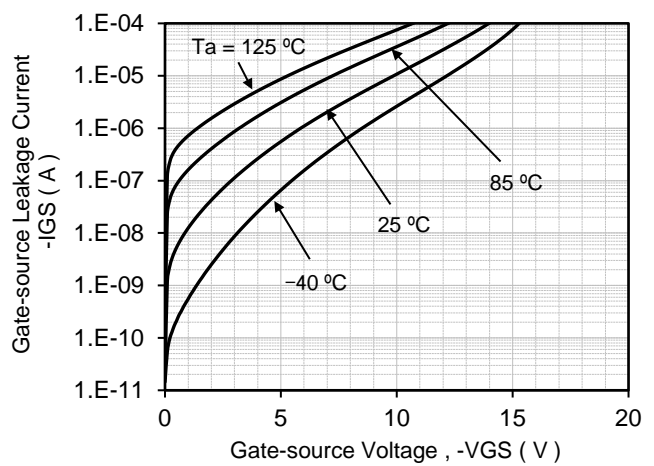
RDS(on) - VGS<sup>\*1</sup>



IF - VF(s-d)<sup>\*1</sup>



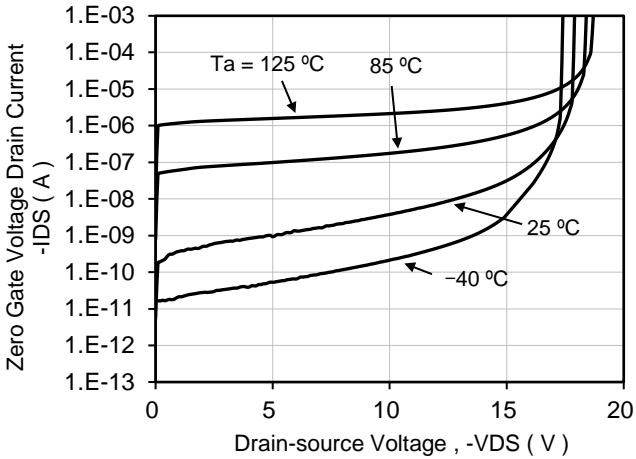
IGS - VGS<sup>\*1</sup>



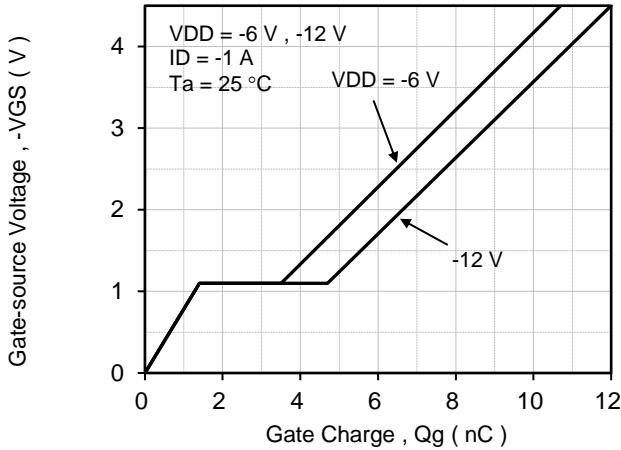


Technical Data ( reference )

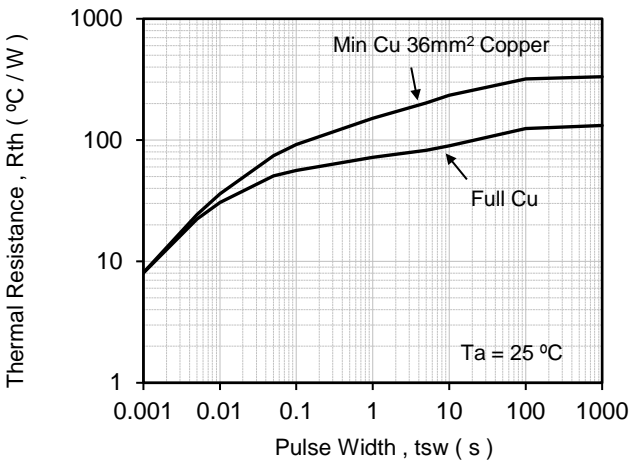
IDS - VDS<sup>\*1</sup>



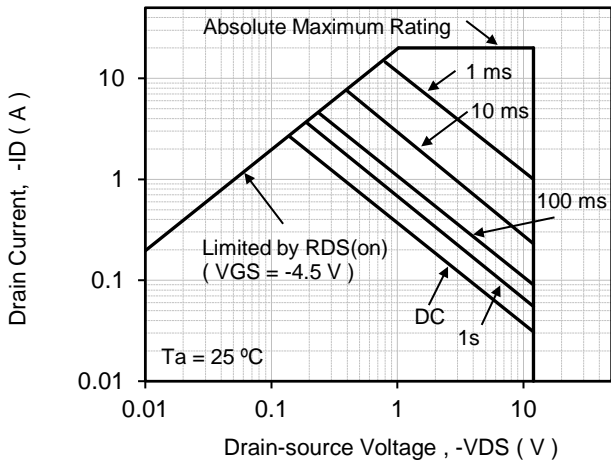
Dynamic Input / Output Characteristics



Rth - tsw<sup>\*2\*3</sup>



Safe Operating Area<sup>\*2</sup>

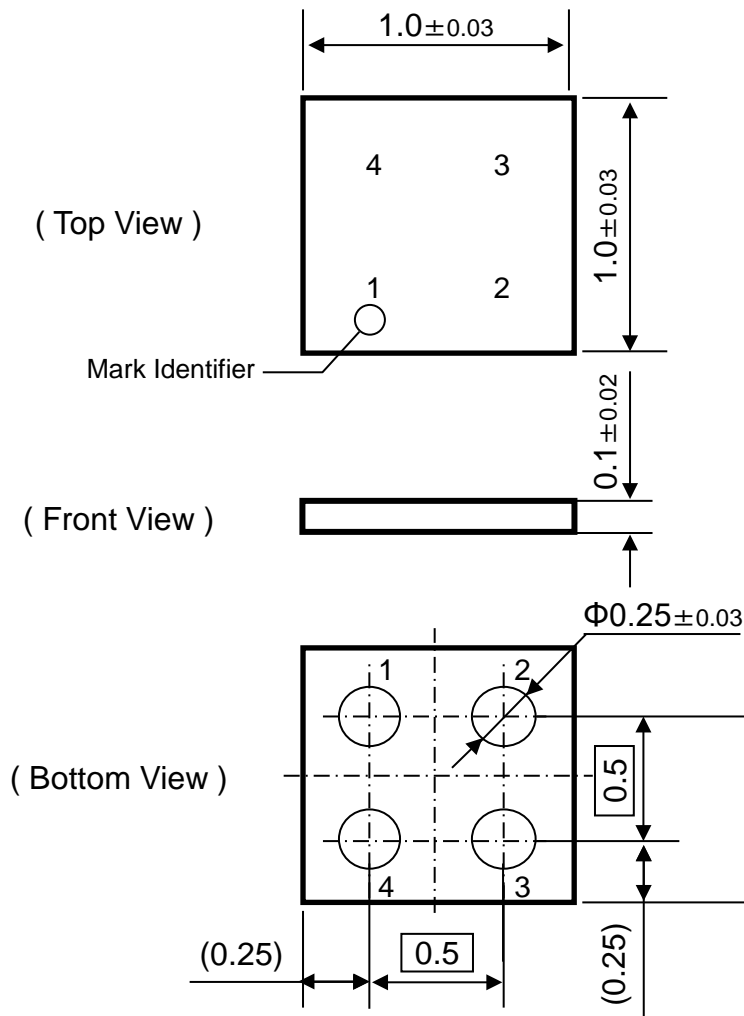


Note

- \*1 Pulse measurement
- \*2 FR4 board (25.4mm×25.4mm×1.0mm), Min Cu 36mm<sup>2</sup> Copper.
- \*3 FR4 board (25.4mm×25.4mm×1.0mm), Full Cu.

■ Outline

Unit: mm



■ Land & Stencil Pattern ( Reference )

Unit: mm

